

MATERIAL DECLARATION SHEET



Material Number	CAY10-J2 (LF)			
Product Line	Chip Resistor Array			
Compliance Date	2012/7/18			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CAS if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00081889714	Aluminum oxide	1344-28-1	96%	76.05%	79.22%
				Silicon dioxide	14808-60-7	4%	3.17%	
2	Conductor Layer	Other	0.00003907386	Silver	7440-22-4	95%	3.59%	3.78%
				Glass	65997-18-4	5%	0.19%	
3	Resistive Element	Other	0.00002594587	Ruthenium dioxide	12036-10-1	25%	0.63%	2.01%
				Silver	7440-22-4	40%	1%	
				Palladium	7440-05-3	15%	0.38%	
4	Over-Coating	Paint	0.00002470543	Lead oxide	1317-36-8	20%	0.5%	2.89%
				Epoxy	25068-38-6	100%	2.39%	
5	End Terminal	Metal	0.00003700646	Nickel	7440-02-0	80%	2.86%	2.86%
6	Ni Plating	Metal	0.00004837716	Chromium	7440-47-3	20%	0.72%	5.4%
				Nickel	7440-02-0	100%	4.68%	
7	Tin Plating	Metal	0.00003969408	Tin	7440-31-5	100%	3.84%	3.84%
		Total weight	0.0010337					

This Document was updated on: **2012/7/23**

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I